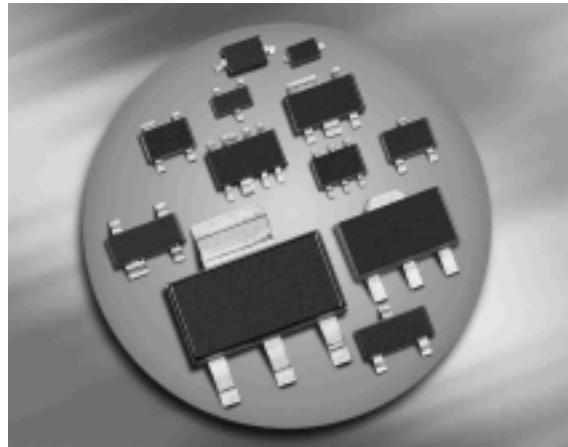


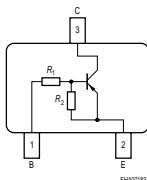
### PNP Silicon Digital Transistor

- Switching circuit, inverter, interface circuit, driver circuit
- Built in bias resistor ( $R_1 = 100\text{k}\Omega$ ,  $R_2 = 100\text{k}\Omega$ )



**BCR151F/L3**

**BCR151T**



Type	Marking	Pin Configuration						Package
BCR151F*	UDs	1=B	2=E	3=C	-	-	-	TSFP-3
BCR151L3*	UD	1=B	2=E	3=C	-	-	-	TSLP-3-4
BCR151T*	UD	1=B	2=E	3=C	-	-	-	SC75

\* Preliminary

### Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CEO}$	50	V
Collector-base voltage	$V_{CBO}$	50	
Input forward voltage	$V_i(\text{fwd})$	20	
Input reverse voltage	$V_i(\text{rev})$	10	
Collector current	$I_C$	50	mA
Total power dissipation- BCR151F, $T_S \leq 128^\circ\text{C}$	$P_{\text{tot}}$	250	mW
BCR151L3, $T_S \leq 135^\circ\text{C}$		250	
BCR151T, $T_S \leq 109^\circ\text{C}$		250	
Junction temperature	$T_j$	150	°C
Storage temperature	$T_{\text{stg}}$	-65 ... 150	

**Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>1)</sup> BCR151F	$R_{thJS}$	$\leq 90$	K/W
BCR151L3		$\leq 60$	
BCR151T		$\leq 165$	

**Electrical Characteristics at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

**DC Characteristics**

Collector-emitter breakdown voltage $I_C = 100 \mu\text{A}, I_B = 0$	$V_{(\text{BR})\text{CEO}}$	50	-	-	V
Collector-base breakdown voltage $I_C = 10 \mu\text{A}, I_E = 0$	$V_{(\text{BR})\text{CBO}}$	50	-	-	
Collector-base cutoff current $V_{CB} = 40 \text{ V}, I_E = 0$	$I_{\text{CBO}}$	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 10 \text{ V}, I_C = 0$	$I_{\text{EBO}}$	-	-	75	$\mu\text{A}$
DC current gain <sup>2)</sup> $I_C = 5 \text{ mA}, V_{CE} = 5 \text{ V}$	$h_{\text{FE}}$	70	-	-	-
Collector-emitter saturation voltage <sup>2)</sup> $I_C = 5 \text{ mA}, I_B = 0.25 \text{ mA}$	$V_{\text{CEsat}}$	-	-	0.3	V
Input off voltage $I_C = 100 \mu\text{A}, V_{CE} = 5 \text{ V}$	$V_{i(\text{off})}$	0.5	-	1.8	
Input on voltage $I_C = 1 \text{ mA}, V_{CE} = 0.3 \text{ V}$	$V_{i(\text{on})}$	1	-	3	
Input resistor	$R_1$	70	100	130	k $\Omega$
Resistor ratio	$R_1/R_2$	0.9	1	1.1	-

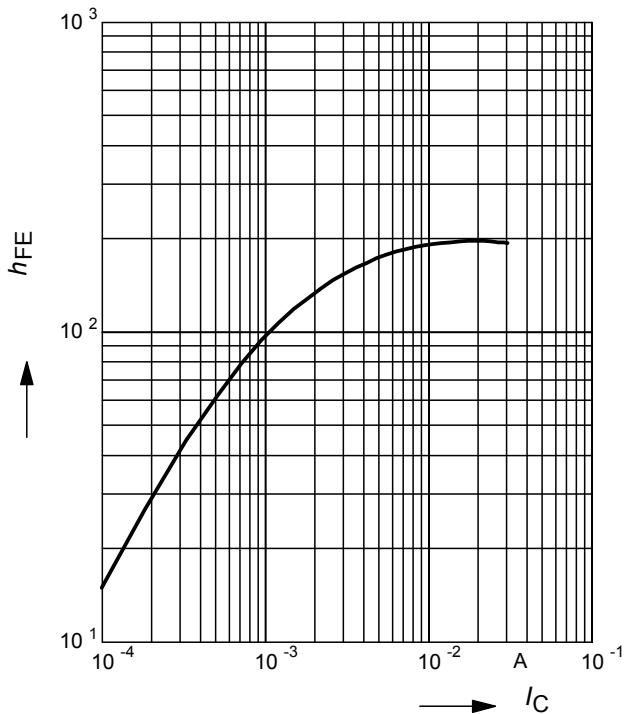
**AC Characteristics**

Transition frequency $I_C = 10 \text{ mA}, V_{CE} = 5 \text{ V}, f = 100 \text{ MHz}$	$f_T$	-	120	-	MHz
Collector-base capacitance $V_{CB} = 10 \text{ V}, f = 100 \text{ MHz}$	$C_{cb}$	-	3	-	pF

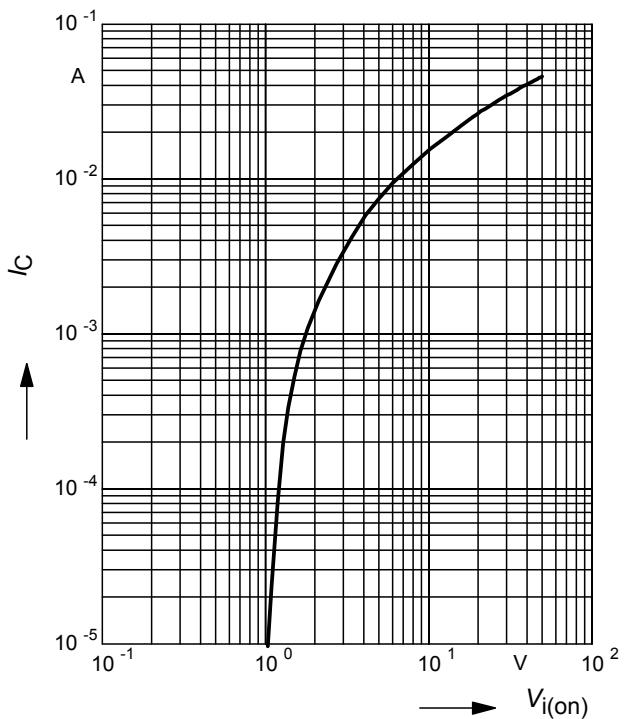
<sup>1</sup>For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

<sup>2</sup>Pulse test:  $t < 300 \mu\text{s}$ ;  $D < 2\%$

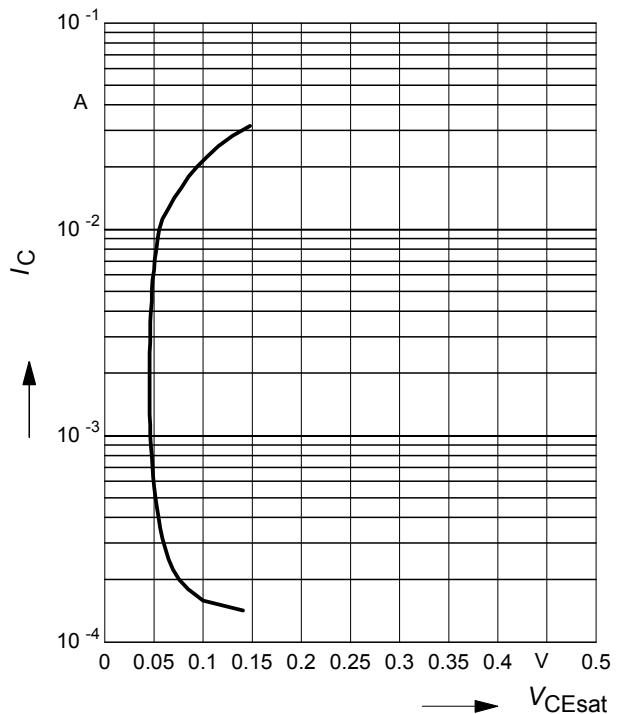
**DC current gain**  $h_{FE} = f(I_C)$   
 $V_{CE} = 5 \text{ V}$  (common emitter configuration)



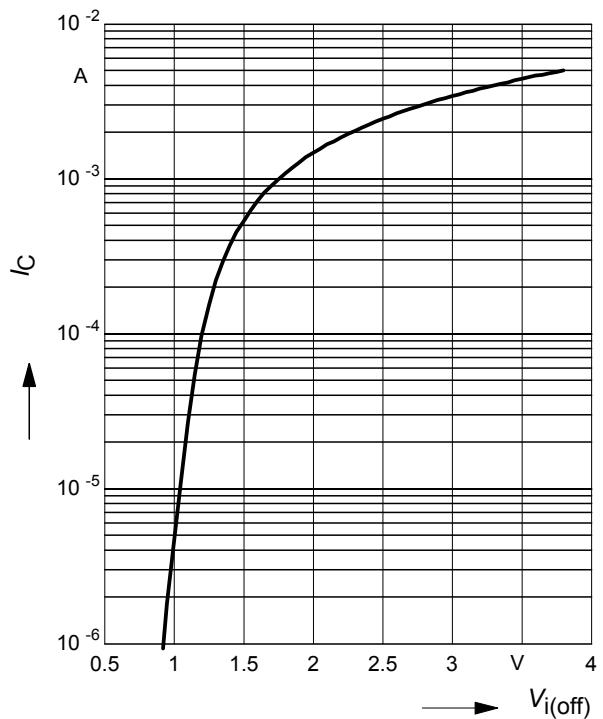
**Input on Voltage**  $V_{i(on)} = f(I_C)$   
 $V_{CE} = 0.3 \text{ V}$  (common emitter configuration)



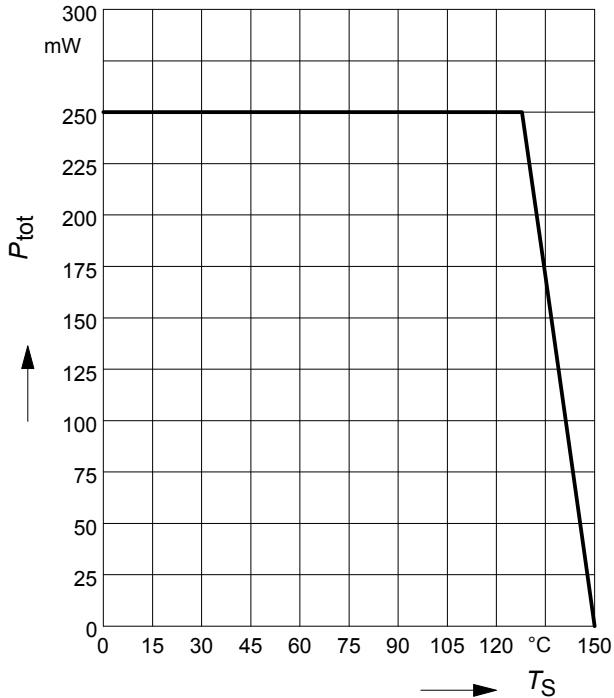
**Collector-emitter saturation voltage**  
 $V_{CEsat} = f(I_C)$ ,  $h_{FE} = 20$



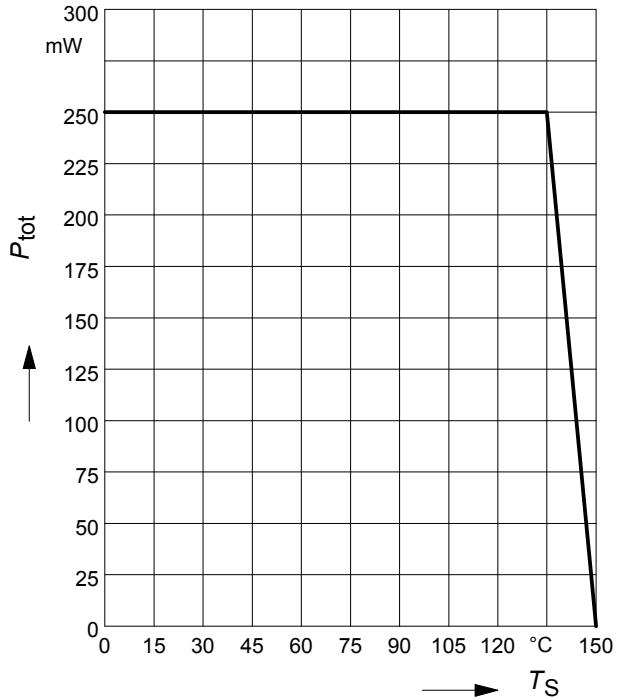
**Input off voltage**  $V_{i(off)} = f(I_C)$   
 $V_{CE} = 5 \text{ V}$  (common emitter configuration)



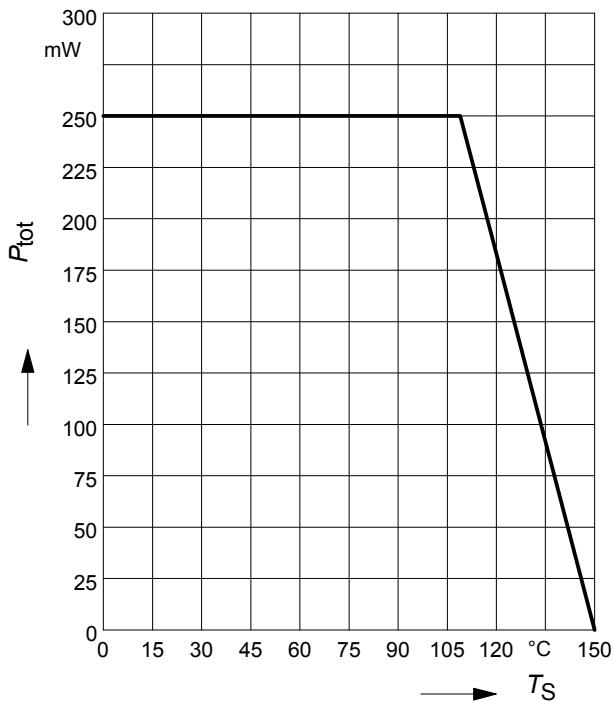
**Total power dissipation  $P_{\text{tot}} = f(T_S)$**   
BCR151F



**Total power dissipation  $P_{\text{tot}} = f(T_S)$**   
BCR151L3

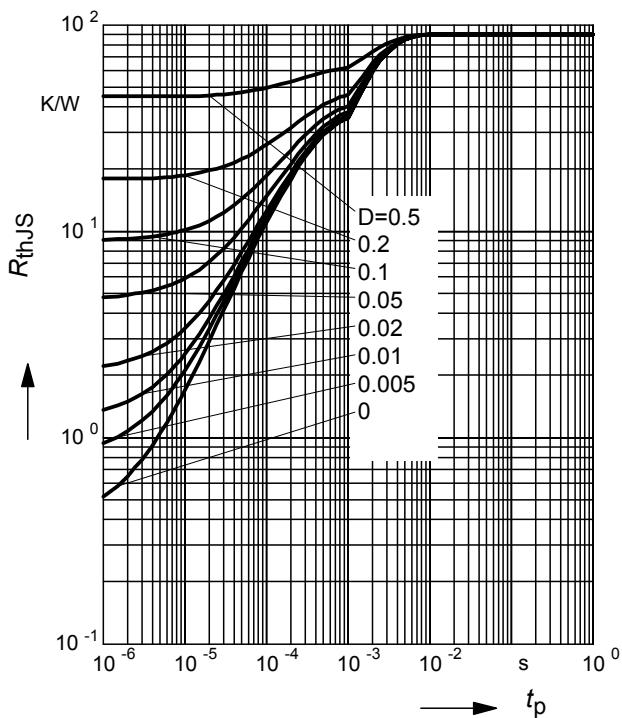


**Total power dissipation  $P_{\text{tot}} = f(T_S)$**   
BCR151T

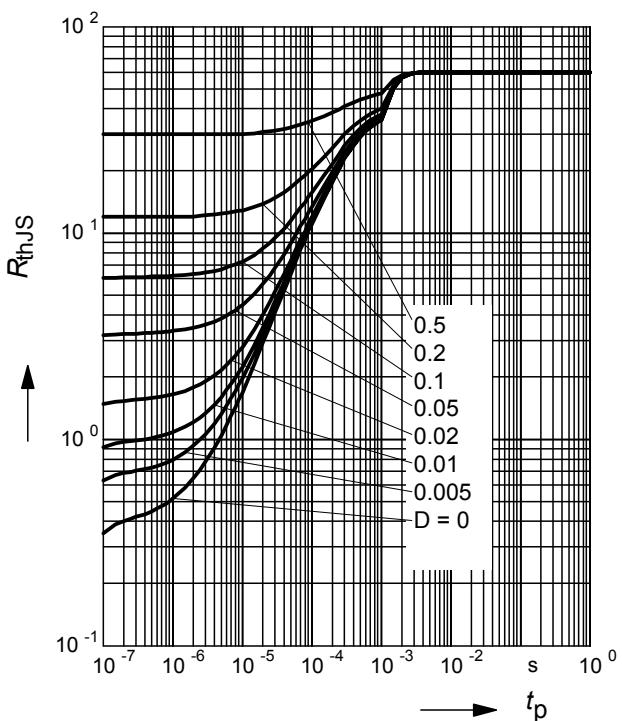


**Permissible Puls Load  $R_{\text{thJS}} = f(t_p)$** 

BCR151F

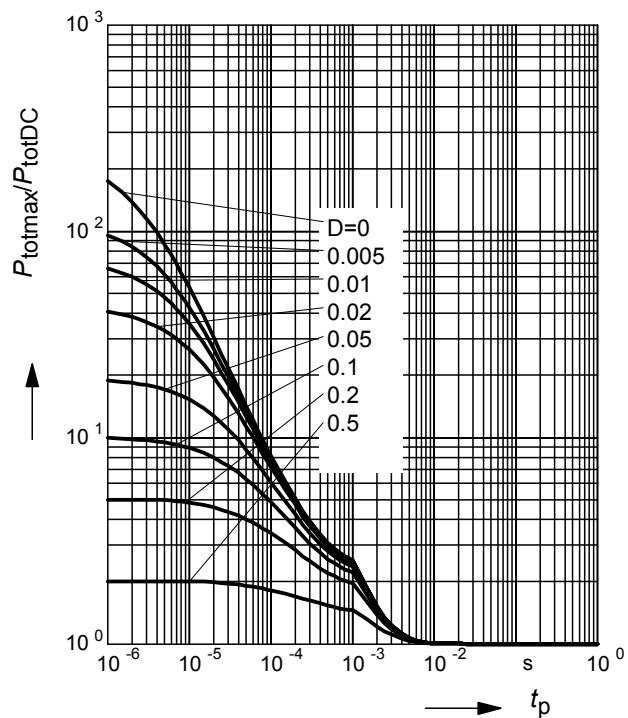

**Permissible Puls Load  $R_{\text{thJS}} = f(t_p)$** 

BCR151L3


**Permissible Pulse Load**

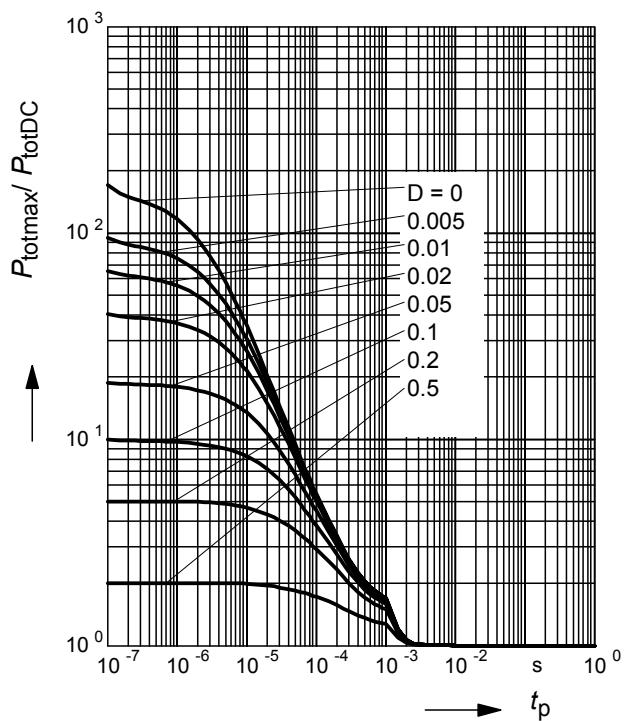
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

BCR151F


**Permissible Pulse Load**

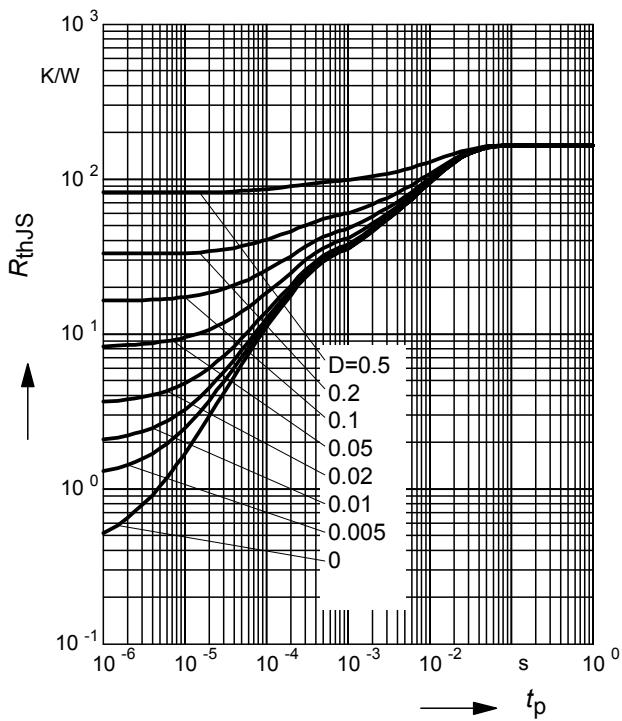
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

BCR151L3



**Permissible Puls Load**  $R_{\text{thJS}} = f(t_p)$

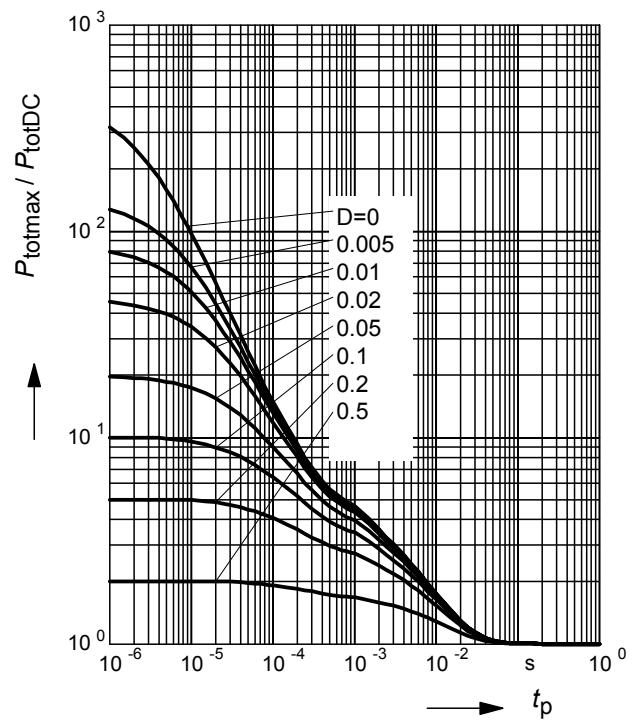
BCR151T



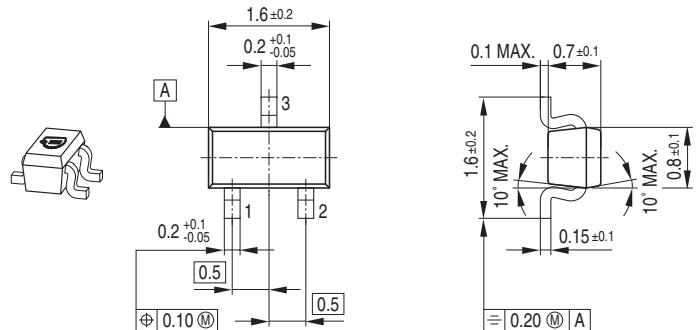
**Permissible Pulse Load**

$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$

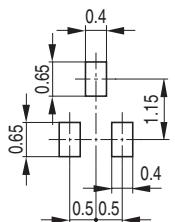
BCR151T



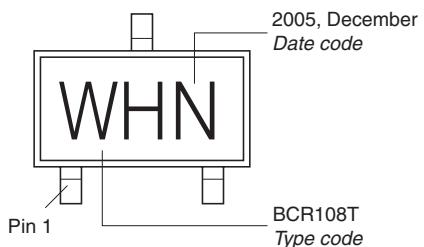
### Package Outline



### Foot Print

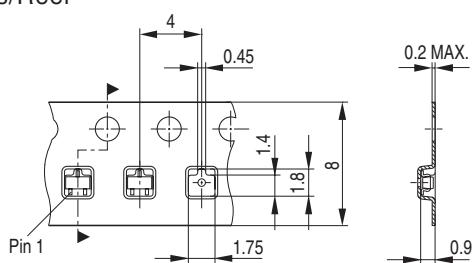


### Marking Layout (Example)



### Standard Packing

Reel  $\varnothing 180 \text{ mm} = 3.000 \text{ Pieces/Reel}$   
 Reel  $\varnothing 330 \text{ mm} = 10.000 \text{ Pieces/Reel}$

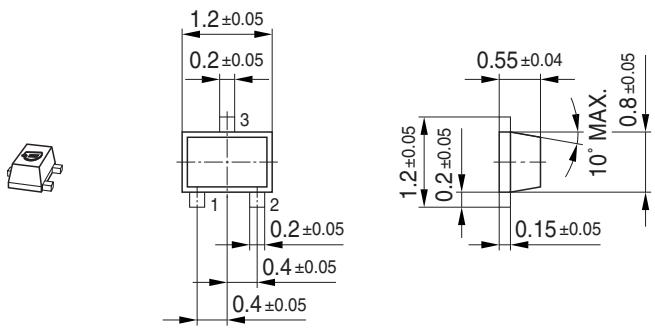


Date Code marking for discrete packages with  
one digit (SCD80, SC79, SC75<sup>1)</sup>) CES-Code

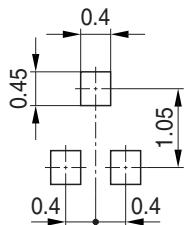
Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

1) New Marking Layout for SC75, implemented at October 2005.

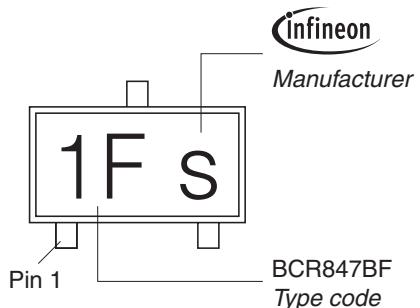
## Package Outline



## Foot Print

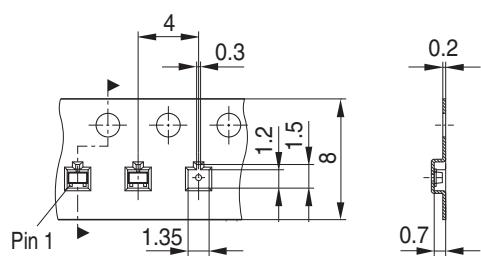


## Marking Layout (Example)

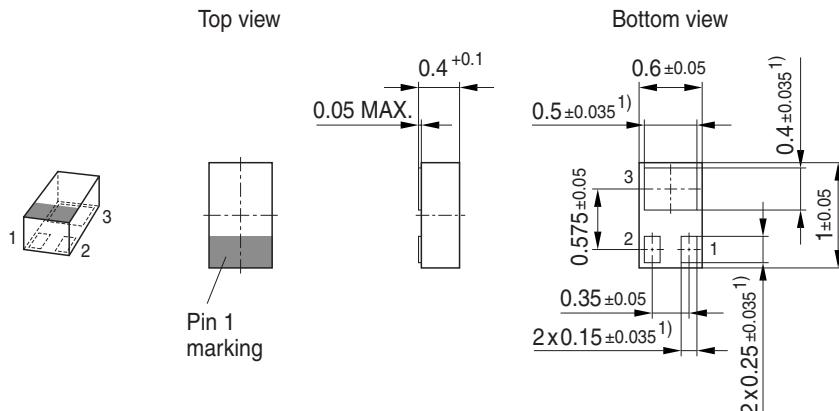


## Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel  
 Reel ø330 mm = 10.000 Pieces/Reel

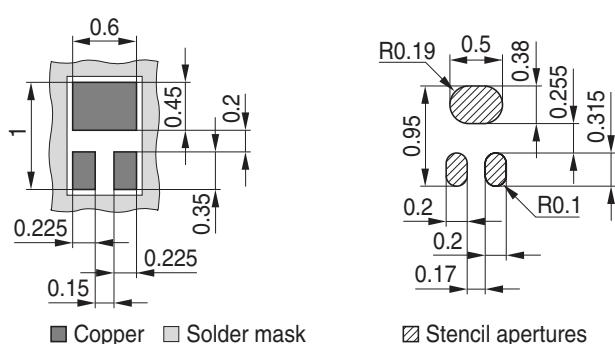


### Package Outline

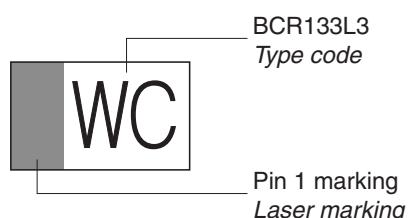


### Foot Print

For board assembly information please refer to Infineon website "Packages"

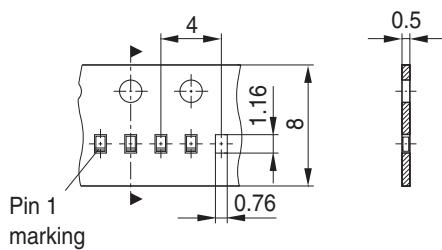


### Marking Layout



### Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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